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AMENDMENT TO THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A multi-functioned wafer aligner comprising:

a multi-functioned unit for performing a wafer centering operation, a wafer flat zone alignment, and a wafer damage detection;

the multi-functioned unit comprising:

a wafer rotator;

an array of luminous emitters for emitting incident rays toward a wafer disposed on the wafer rotator; and

an array of damage-detecting sensors for receiving the incident rays reflected from edges of the wafer to detect wafer damage; and
a main processor for determining deciding positions of the wafer centering operation and the wafer flat zone alignment, and discriminating wafer damage, such as wafer breakage and wafer crack, by calculating an accumulated digital signal inputted from the multi-functioned unit.

2. (Currently Amended) The multi-functioned wafer aligner of claim 1, wherein the multi-functioned unit further comprises:

a wafer rotator;

an array of multiple luminous emitters for emitting incident rays;

an array of multiple photo detecting sensors for receiving reflected the incident rays emitted from the wafer array of luminous emitters to detect a wafer position and a

wafer flat zone, wherein each the photo detecting sensors faces are disposed opposed to
each the luminous emitters; and

~~an array of multiple damage detecting sensors for receiving reflected rays from
edge of the wafer to detect wafer damage.~~

3. (Currently Amended) The multi-functioned wafer aligner of claim 2, wherein ~~a first area in the array of multiple damage detecting sensors receives reflected rays when the wafer is not damaged, and a second area in the array of multiple damage detecting sensors receives reflected rays when the wafer is damaged~~ the array of ~~multiple~~ photo detecting sensors receive no incident ray when the wafer interrupts the incident rays from the array of ~~multiple~~ luminous emitters.

4. (Currently Amended) The multi-functioned wafer aligner of claim 36, wherein the main processor further comprises an alarm unit when the second area receives reflected rays.

5. (Currently Amended) The multi-functioned wafer aligner of claim 21, wherein the multi-functioned unit comprises an array of ~~multiple~~ luminous emitters for emitting incident rays to the edge of ~~the front side of~~ the wafer and ~~an array of multiple luminous emitters for emitting incident rays to the edge of the back side of~~ the wafer.

6. (Currently Amended) The multi-functioned wafer aligner of claim 51, wherein a first area in the array of ~~multiple~~ damage-detecting sensors receives reflected rays when the

wafer is not damaged, and a second area in the array of ~~multiple~~ damage-detecting sensors receives reflected rays when the wafer is damaged.

7. (Currently Amended) A multi-functioned wafer aligner comprising:

a rotatable ~~rotation~~ chuck, adapted to receive a semiconductor wafer;

a wafer transfer unit, adapted to position said wafer upon said ~~rotation~~ rotatable chuck;

a sensor body, ~~said sensor body~~ comprising:

a position compensator; ~~and~~

a luminous source; and

a wafer damage detector comprising an array of damage-detecting sensors adapted to receive light emitted from said luminous source that is reflected off of the edge of said wafer;

wherein said sensor body is disposed in relation to said ~~rotation~~ rotatable chuck so as to receive an edge of said wafer within said position compensator.

8. (Currently Amended) The apparatus of claim 7, wherein said position compensator ~~further~~ comprises:

~~a luminous source disposed on a first side of said edge of said wafer; and~~

~~a photodetector disposed upon an opposing side of said edge of said wafer the luminous source, said photodetector adapted to receive light emitted by said luminous source.~~

9. Cancelled

10. (Currently Amended) A method ~~multifunctionally for~~ positioning a wafer and detecting wafer damage, said method comprising:

providing a luminous source on a first side of an edge of said wafer;

providing a photodetector on an opposing side of said wafer, said photodetector adapted to receive light emitted by said luminous source;

providing ~~a damage-detecting array of~~ an array of damage-detecting sensors adapted to receive light emitted from said luminous source that is reflected off of said wafer edge;

rotating said wafer;

determining the position of said wafer by examination of light received by said photodetector; and

inspecting for damage to said wafer by examining the light received by said ~~damage-detecting~~ array of damage-detecting sensors.